



## Product Change Notification: MFOL-15RYZV597

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### Date:

22-Jul-2025

### Product Category:

Platform Root Of Trust Controllers

### Notification Subject:

CCB 7657 Initial Notice: Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

### Affected CPNs:

[MFOL-15RYZV597\\_Affected\\_CPN\\_07222025.pdf](#)

[MFOL-15RYZV597\\_Affected\\_CPN\\_07222025.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

### Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD/ (ANAC)	Amkor Assembly & Test (Shanghai) Co., LTD/ (ANAC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Substrate Core Material	HL832NXA	HL832NXA	HL832NXA
Substrate SM Material	AUS320	AUS320	AUS320
Die Attach Material	HR9004-20	HR9004-20	EM760L2-P

<b>Wire Material</b>	CuPdAu	CuPdAu	CuPdAu
<b>Molding Compound Material</b>	G750E	G750E	G750E

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** November 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	<b>July 2025</b>					>	<b>November 2025</b>				
<b>Work Week</b>	27	28	29	30	31		45	46	47	48	49
<b>Initial PCN Issue Date</b>				X							
<b>Qual Report Availability</b>											X
<b>Final PCN Issue Date</b>											X

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** July 22, 2025: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**[PCN\\_MFOL-15RYZV597\\_Qual Plan.pdf](#)**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

CEC1702Q-B2-I/SX  
CEC1702Q-B1-SX-CN1  
CEC1702Q-C1-SX  
CEC1712H-N2-I/SX-BMGP1-TR  
CEC1712H-S2-I/SX-DE2-TR  
CEC1712H-N2-I/SX-DL1  
CEC1712H-S2-I/SX-DE2  
CEC1712H-S2-I/SX  
CEC1712H-S2-I/SX-GM  
CEC1712H-N2-I/SX-BMGP2  
CEC1712H-N2-I/SX-BMGP3  
CEC1712H-N2-I/SX-BMGP1  
CEC1712H-N2-I/SX  
CEC1712H-N2-I/SX-LU1  
CEC1712H-B2-I/SX  
CEC1702Q-B1-SX-CN2  
CEC1702Q-B2-E/SXVAO  
CEC1712H-N2-I/SX-TG1  
CEC1702Q-S1-I/SX  
CEC1702Q-B1-SX-TR  
CEC1702Q-C2-I/SX  
CEC1702Q-B1-SX  
CEC1712H-S2-E/SXVAO  
CEC1702Q-B2-I/SX-SM1



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## **QUALIFICATION PLAN SUMMARY**

**PCN #: MFOL-15RYZV597**

**Date:**  
**July 15, 2025**

**Qualification of ATP7 as an additional assembly site for  
CEC1702 and CEC1712 device families available in 84L  
WFBGA (7x7x0.8mm) package.**

**Purpose:** Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

**CCB No.:** 7657

<b><u>Misc.</u></b>	Assembly site	ATP7
	MP Code (MPC)	See MPC List
	Part Number (CPN)	See CPN List
	MSL information	3/260
	Assembly Shipping Media (T/R, Tube/Tray)	Tray (UB07070.751026XA)
	Base Quantity Multiple (BQM)	260
	Reliability Site	MTAI
<b><u>Substrate</u></b>	Core Material	HL832NXA
	Core Thickness	0.06 mm
	SM Material	AUS320
	Process	STD
	SM Thickness	0.02/0.02 mm
	Part Number	101413722
	Drill Size	100um
<b><u>Bond Wire</u></b>	Material	CuPdAu
<b><u>Die Attach 1</u></b>	Part Number	EM760L2-P
	Conductive	No
<b><u>MC</u></b>	Part Number	G750E
<b><u>PKG</u></b>	Package Type	WFBGA
	Pin/Ball Count	84
	PKG width/size	7x7x0.8mm
	Ball Pitch/Size	0.65/0.25 mm
	Solder Ball Material	SAC105

Test Name	Conditions	Reliability Stress Read Point	Pre & Post Reliability Stress Test Temperature	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instruction
Wire Bond Pull - WBP	Mil. Std. 883-2011			5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001			5	0	1	5		5	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108			10	0	3	30		5	
External Visual	Mil. Std. 883-2009/2010			All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	'JESD22-A103 +125°C, +150°C or +175°C  2x Stress	1st Readpoint: Grade 1: 500 hrs (+175°C)  2nd Readpoint: Grade 1: 1000 hrs (+175°C)	Grade 1: +25°C, +125°C	45	5	3	150	0	21-67	Perform per the requirements in AEC-Q100/Q101. Spares should be properly identified.
Preconditioning - Required for surface mount devices	'J-STD-020 JESD22-A113  +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type.		Grade 1: +25°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.

Test Name	Conditions	Reliability Stress Read Point	Pre & Post Reliability Stress Test Temperature	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instruction
<b>HAST</b>	'JESD22-A101 or A110 +130°C/85% RH for 96 hrs or +110°C/85%RH for 264 hrs  2x Stress	1st Readpoint: Grade 1: 96 hrs (+130°C/85% RH)  2nd Readpoint: Grade 1: 192 hrs (+130°C/85% RH)	Grade 1: +25°C, +125°C	77	5	3	246	0	10-22	Perform per the requirements in AEC-Q006. Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
<b>uHAST</b>	'JESD22-A102, A118, or A101  +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs	Grade 1: 96 hrs (+130°C/85% RH)	Grade 1: +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
<b>Temp Cycle</b>	'JESD22-A104 and Appendix 3 -55°C to +125°C, -55°C to +150°C 2x Stress	1st Readpoint: Grade 1: 1000 cycles (-55°C to +150°C)  2nd Readpoint: Grade 1: 2000 cycles (-55°C to +150°C)	Grade 1: +25°C, +125°C	77	5	3	246	0	15-120	Perform per the requirements in AEC-Q006. Spares should be properly identified. Use the parts which have gone through Pre-conditioning.